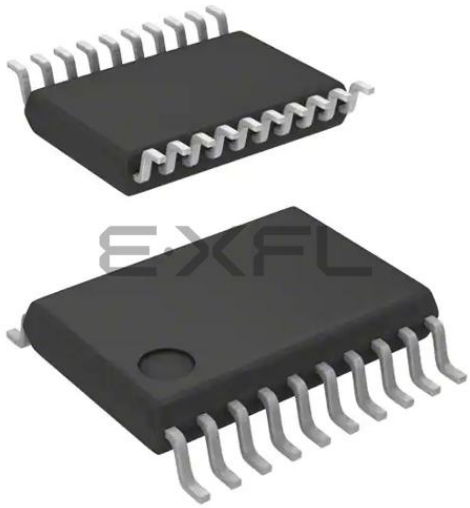

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I²C, SIO, UART/USART
Peripherals	LED, POR, Voltage Detect, WDT
Number of I/O	13
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 4x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-LSSOP (0.173", 4.40mm Width)
Supplier Device Package	20-LSSOP
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f21164dsp-u0

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1.2 Performance Overview

Table 1.1 lists the Performance Outline of the R8C/16 Group and Table 1.2 lists the Performance Outline of the R8C/17 Group.

Table 1.1 Performance Outline of the R8C/16 Group

Item		Performance
CPU	Number of Basic Instructions	89 instructions
	Minimum Instruction Execution Time	50ns(f(XIN)=20MHz, VCC=3.0 to 5.5V) 100ns(f(XIN)=10MHz, VCC=2.7 to 5.5V)
	Operating Mode	Single-chip
	Address Space	1 Mbyte
	Memory Capacity	See **Table 1.3 R8C/16 Group Product Information**
Peripheral Function	Port	I/O port : 13 pins (including LED drive port), Input : 2 pins
	LED Drive Port	I/O port: 4 pins
	Timer	Timer X: 8 bits × 1 channel, Timer Z: 8 bits × 1 channel (Each timer equipped with 8-bit prescaler) Timer C: 16 bits × 1 channel (Circuits of input capture and output compare)
	Serial Interface	1 channel Clock synchronous serial I/O, UART
	I²C bus Interface (IIC)(1)	1 channel
	A/D Converter	10-bit A/D converter: 1 circuit, 4 channels
	Watchdog Timer	15 bits × 1 channel (with prescaler) Reset start selectable, Count source protection mode
	Interrupt	Internal: 9 factors, External: 4 factors, Software: 4 factors Priority level: 7 levels
	Clock Generation Circuit	2 circuits Main clock oscillation circuit (Equipped with a built-in feedback resistor) On-chip oscillator (high speed, low speed) Equipped with frequency adjustment function on high-speed on-chip oscillator
	Oscillation Stop Detection Function	Main clock oscillation stop detection function
	Voltage Detection Circuit	Included
	Power-on Reset Circuit	Included
Electric Characteristics	Supply Voltage	VCC=3.0 to 5.5V (f(XIN)=20MHz) VCC=2.7 to 5.5V (f(XIN)=10MHz)
	Power Consumption	Typ. 9mA (VCC=5.0V, f(XIN)=20MHz) Typ. 5mA (VCC=3.0V, f(XIN)=10MHz) Typ. 35μA (VCC=3.0V, wait mode, peripheral clock off) Typ. 0.7μA (VCC=3.0V, stop mode)
Flash Memory	Program/Erase Supply Voltage	VCC=2.7 to 5.5V
	Program/Erase Endurance	100 times
Operating Ambient Temperature		-20 to 85°C -40 to 85°C (D Version)
Package		20-pin plastic mold LSSOP

NOTES:
1. I²C bus is a trademark of Koninklijke Philips Electronics N. V.

Table 1.2 Performance Outline of the R8C/17 Group

Item		Performance
CPU	Number of Basic Instructions	89 instructions
	Minimum Instruction Execution Time	50ns(f(XIN)=20MHz, VCC=3.0 to 5.5V) 100ns(f(XIN)=10MHz, VCC=2.7 to 5.5V)
	Operating Mode	Single-chip
	Address Space	1 Mbyte
	Memory Capacity	See **Table 1.4 R8C/17 Group Product Information**
Peripheral Function	Port	I/O : 13 pins (including LED drive port), Input : 2 pin
	LED drive port	I/O port: 4 pins
	Timer	Timer X: 8 bits × 1 channel, Timer Z: 8 bits × 1 channel (Each timer equipped with 8-bit prescaler) Timer C: 16 bits × 1 channel (Circuits of input capture and output compare)
	Serial Interface	1 channel Clock synchronous serial I/O, UART
	I^2C bus Interface (IIC)(1)	1 channel
	A/D Converter	10-bit A/D converter: 1 circuit, 4 channels
	Watchdog Timer	15 bits × 1 channel (with prescaler) Reset start selectable, Count source protection mode
	Interrupt	Internal: 9 factors, External: 4 factors, Software: 4 factors Priority level: 7 levels
	Clock Generation Circuit	2 circuits Main clock generation circuit (Equipped with a built-in feedback resistor) On-chip oscillator (high speed, low speed) Equipped with frequency adjustment function on high-speed on-chip oscillator
	Oscillation Stop Detection Function	Main clock oscillation stop detection function
	Voltage Detection Circuit	Included
	Power-on Reset Circuit	Included
Electric Characteristics	Supply Voltage	VCC=3.0 to 5.5V (f(XIN)=20MHz) VCC=2.7 to 5.5V (f(XIN)=10MHz)
	Power Consumption	Typ. 9mA (VCC = 5.0V, f(XIN) = 20MHz) Typ. 5mA (VCC = 3.0V, f(XIN) = 10MHz) Typ.35μA (VCC = 3.0V, wait mode, peripheral clock off) Typ. 0.7μA (VCC = 3.0V, stop mode)
Flash Memory	Program/Erase Supply Voltage	VCC=2.7 to 5.5V
	Program and Erase Endurance	10,000 times (Data flash) 1,000 times (Program ROM)
Operating Ambient Temperature		-20 to 85°C -40 to 85°C (D Version)
Package		20-pin plastic mold LSSOP

NOTES:

1. I^2C bus is a trademark of Koninklijke Philips Electronics N. V.

1.3 Block Diagram

Figure 1.1 shows a Block Diagram.

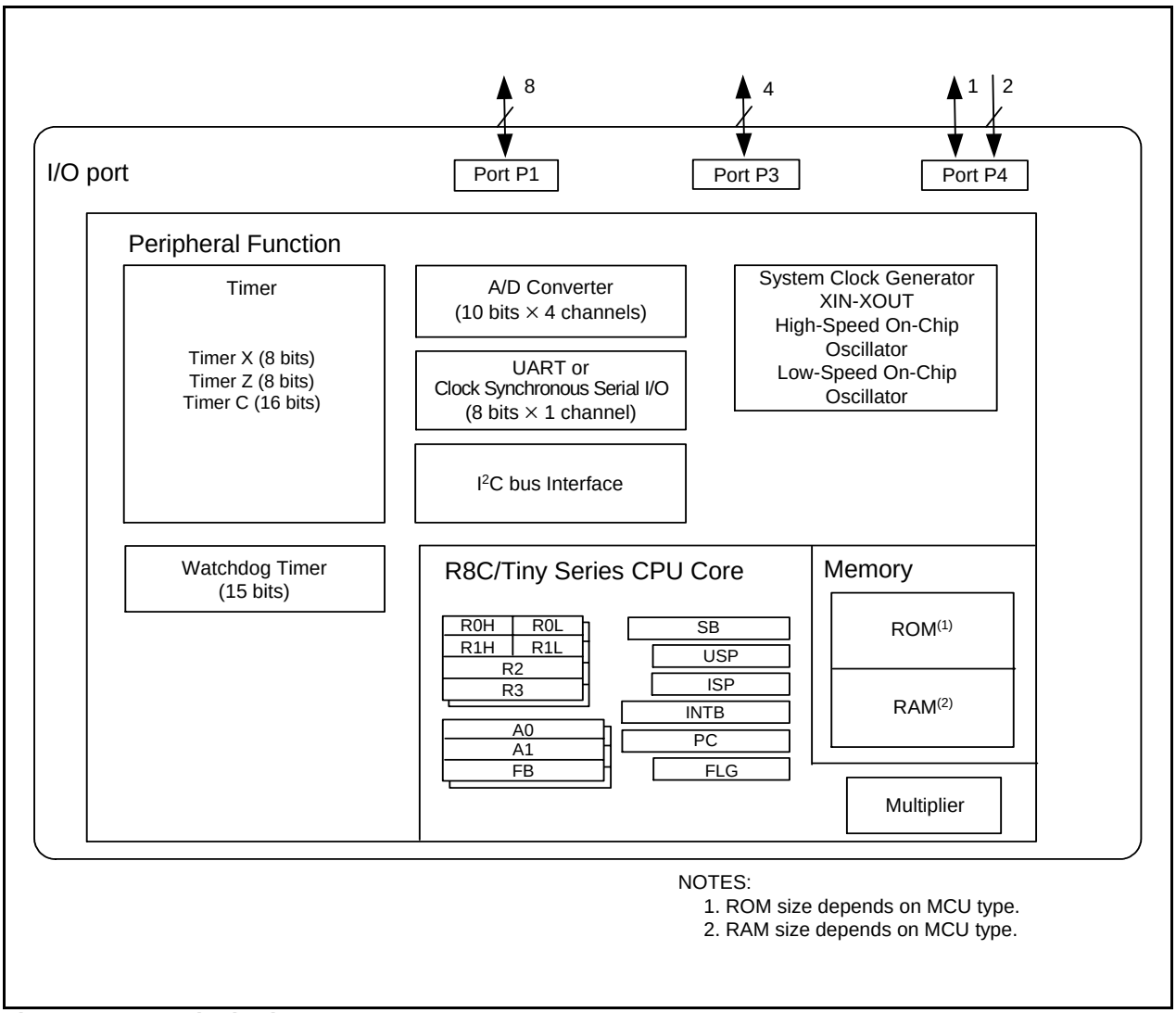


Figure 1.1 Block Diagram

Table 1.4 Product Information of R8C/17 Group **As of Jan 2006**

Type No.	ROM Capacity		RAM Capacity	Package Type	Remarks
	Program ROM	Data flash			
R5F21172SP	8 Kbytes	1 Kbyte × 2	512 bytes	PLSP0020JB-A	Flash Memory Version
R5F21173SP	12 Kbytes	1 Kbyte × 2	768 bytes	PLSP0020JB-A	
R5F21174SP	16 Kbytes	1 Kbyte × 2	1 Kbyte	PLSP0020JB-A	
R5F21172DSP	8 Kbytes	1 Kbyte × 2	512 bytes	PLSP0020JB-A	D Version
R5F21173DSP	12 Kbytes	1 Kbyte × 2	768 bytes	PLSP0020JB-A	
R5F21174DSP	16 Kbytes	1 Kbyte × 2	1 Kbyte	PLSP0020JB-A	

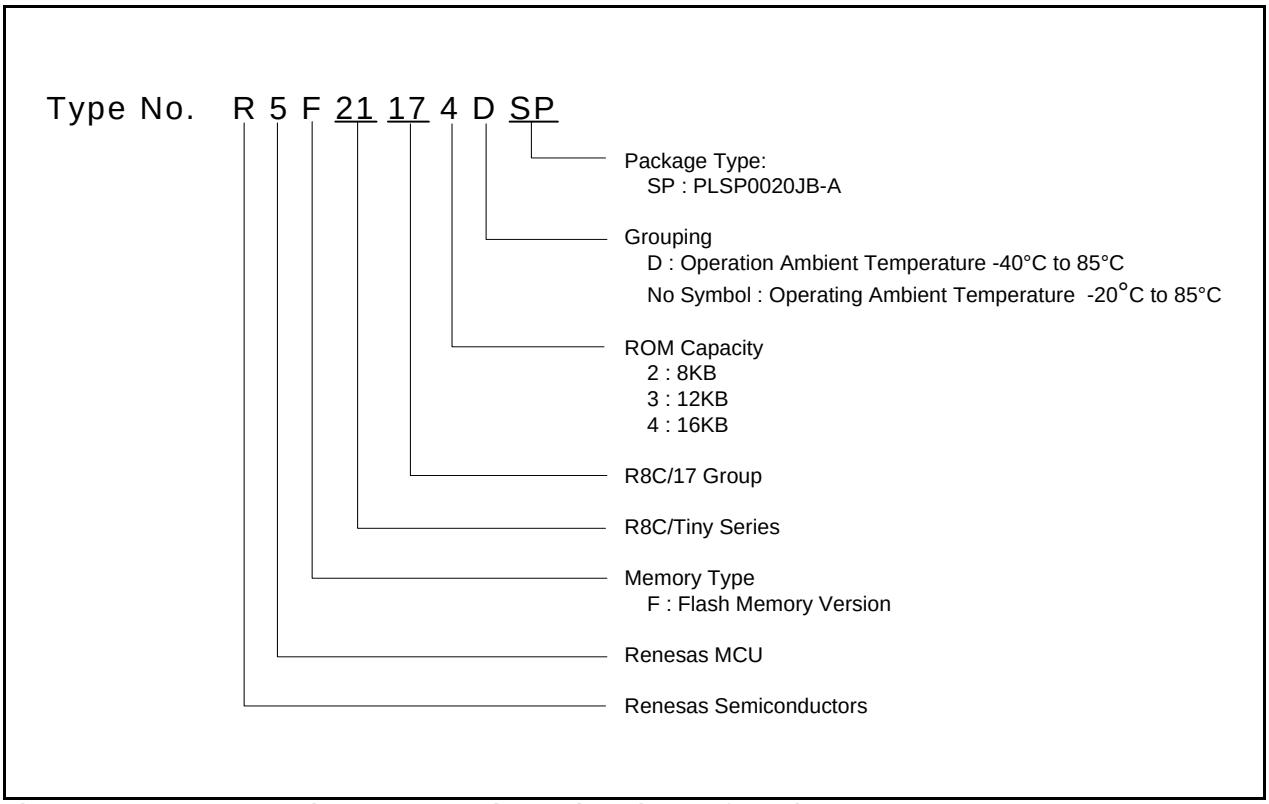


Figure 1.3 Part Number, Memory Size and Package of R8C/17 Group

1.5 Pin Assignments

Figure 1.4 shows the PLSP0020JB-A Package Pin Assignment (top view).

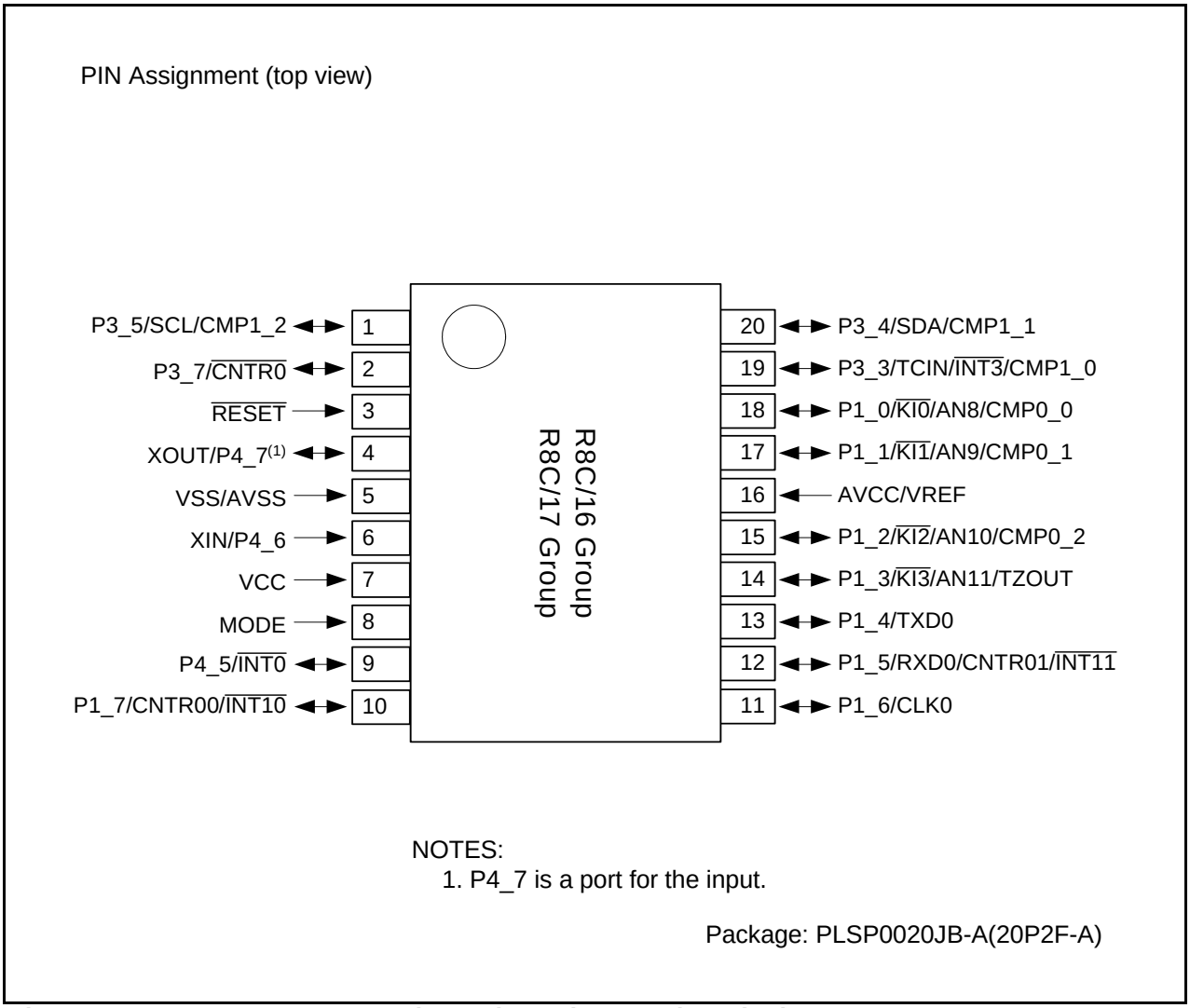


Figure 1.4 PLSP0020JB-A Package Pin Assignment (top view)

1.6 Pin Description

Table 1.5 lists the Pin Description and Table 1.6 lists the Pin Name Information by Pin Number.

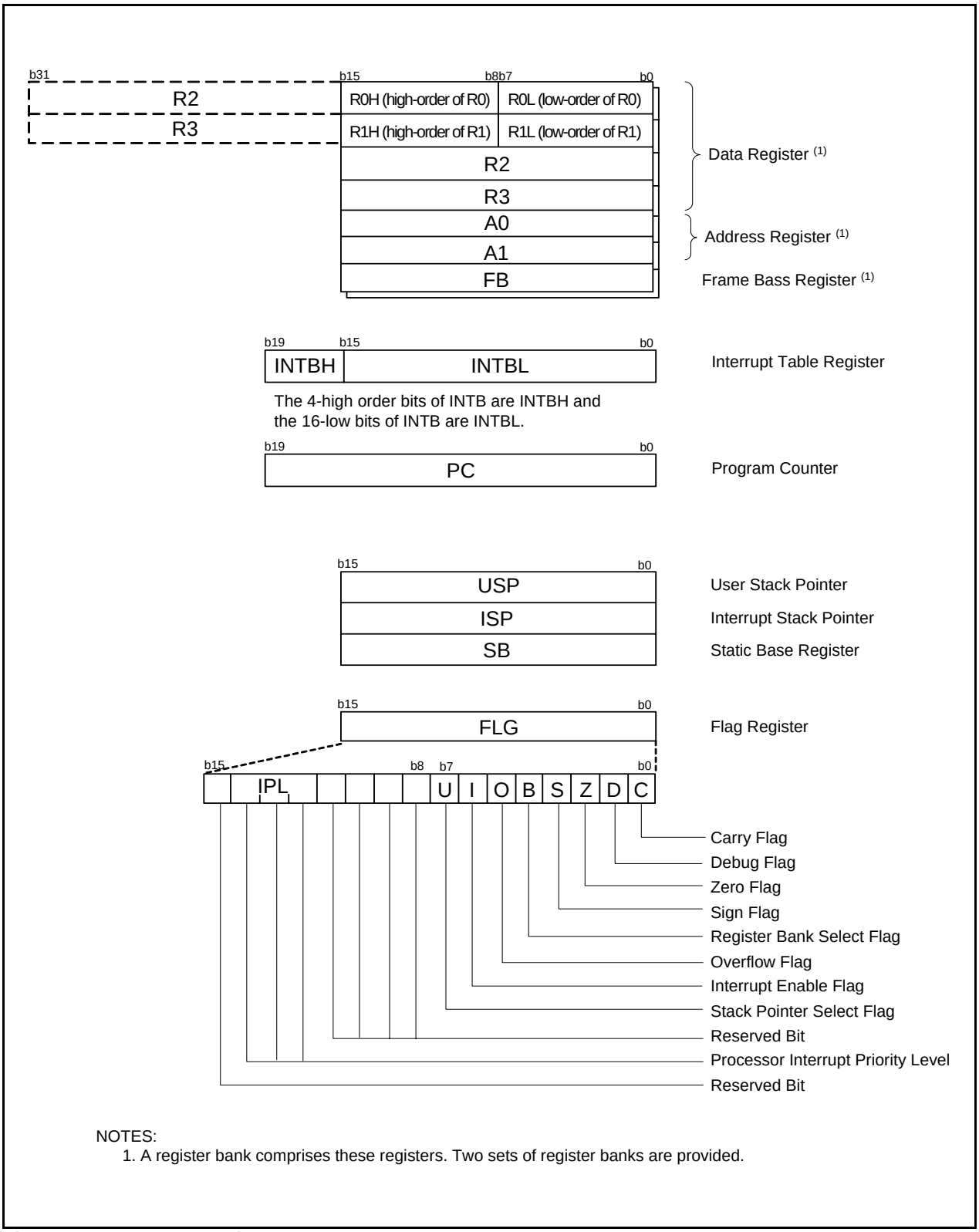
Table 1.5 Pin Description

Function	Pin Name	I/O Type	Description
Power Supply Input	VCC VSS	I	Apply 2.7V to 5.5V to the VCC pin. Apply 0V to the VSS pin
Analog Power Supply Input	AVCC AVSS	I	Power supply input pins to A/D converter. Connect AVCC to VCC. Apply 0V to AVSS. Connect a capacitor between AVCC and AVSS.
Reset Input	$\overline{\text{RESET}}$	I	Input “L” on this pin resets the MCU
MODE	MODE	I	Connect this pin to VCC via a resistor
Main Clock Input	XIN	I	These pins are provided for the main clock generation circuit I/O. Connect a ceramic resonator or a crystal oscillator between the XIN and XOUT pins. To use an externally derived clock, input it to the XIN pin and leave the XOUT pin open.
Main Clock Output	XOUT	O	
$\overline{\text{INT}}$ Interrupt	$\overline{\text{INT0}}$, $\overline{\text{INT1}}$, $\overline{\text{INT3}}$	I	INT interrupt input pins
Key Input Interrupt	$\overline{\text{KI0}}$ to $\overline{\text{KI3}}$	I	Key input interrupt input pins
Timer X	CNTR0	I/O	Timer X I/O pin
	$\overline{\text{CNTR0}}$	O	Timer X output pin
Timer Z	TZOUT	O	Timer Z output pin
Timer C	TCIN	I	Timer C input pin
	CMP0_0 to CMP0_2, CMP1_0 to CMP1_2	O	Timer C output pins
Serial Interface	CLK0	I/O	Transfer clock I/O pin
	RXD0	I	Serial data input pin
	TXD0	O	Serial data output pin
I^2C bus Interface (IIC)	SCL	I/O	Clock I/O pin
	SDA	I/O	Data I/O pin
Reference Voltage Input	VREF	I	Reference voltage input pin to A/D converter Connect VREF to VCC
A/D Converter	AN8 to AN11	I	Analog input pins to A/D converter
I/O Port	P1_0 to P1_7, P3_3 to P3_5, P3_7, P4_5	I/O	These are CMOS I/O ports. Each port contains an I/O select direction register, allowing each pin in that port to be directed for input or output individually. Any port set to input can select whether to use a pull-up resistor or not by program. P1_0 to P1_3 also function as LED drive ports.
Input Port	P4_6, P4_7	I	Port for input-only

I: Input O: Output I/O: Input and output

2. Central Processing Unit (CPU)

Figure 2.1 shows the CPU Register. The CPU contains 13 registers. Of these, R0, R1, R2, R3, A0, A1 and FB comprise a register bank. Two sets of register banks are provided.



NOTES:
1. A register bank comprises these registers. Two sets of register banks are provided.

Figure 2.1 CPU Register

2.1 Data Registers (R0, R1, R2 and R3)

R0 is a 16-bit register for transfer, arithmetic and logic operations. The same applies to R1 to R3. The R0 can be split into high-order bit (R0H) and low-order bit (R0L) to be used separately as 8-bit data registers. The same applies to R1H and R1L as R0H and R0L. R2 can be combined with R0 to be used as a 32-bit data register (R2R0). The same applies to R3R1 as R2R0.

2.2 Address Registers (A0 and A1)

A0 is a 16-bit register for address register indirect addressing and address register relative addressing. They also are used for transfer, arithmetic and logic operations. The same applies to A1 as A0. A0 can be combined with A0 to be used as a 32-bit address register (A1A0).

2.3 Frame Base Register (FB)

FB is a 16-bit register for FB relative addressing.

2.4 Interrupt Table Register (INTB)

INTB is a 20-bit register indicates the start address of an interrupt vector table.

2.5 Program Counter (PC)

PC, 20 bits wide, indicates the address of an instruction to be executed.

2.6 User Stack Pointer (USP) and Interrupt Stack Pointer (ISP)

The stack pointer (SP), USP and ISP, are 16 bits wide each. The U flag of FLG is used to switch between USP and ISP.

2.7 Static Base Register (SB)

SB is a 16-bit register for SB relative addressing.

2.8 Flag Register (FLG)

FLG is a 11-bit register indicating the CPU state.

2.8.1 Carry Flag (C)

The C flag retains a carry, borrow, or shift-out bit that has occurred in the arithmetic logic unit.

2.8.2 Debug Flag (D)

The D flag is for debug only. Set to “0”.

2.8.3 Zero Flag (Z)

The Z flag is set to “1” when an arithmetic operation resulted in 0; otherwise, “0”.

2.8.4 Sign Flag (S)

The S flag is set to “1” when an arithmetic operation resulted in a negative value; otherwise, “0”.

2.8.5 Register Bank Select Flag (B)

The register bank 0 is selected when the B flag is “0”. The register bank 1 is selected when this flag is set to “1”.

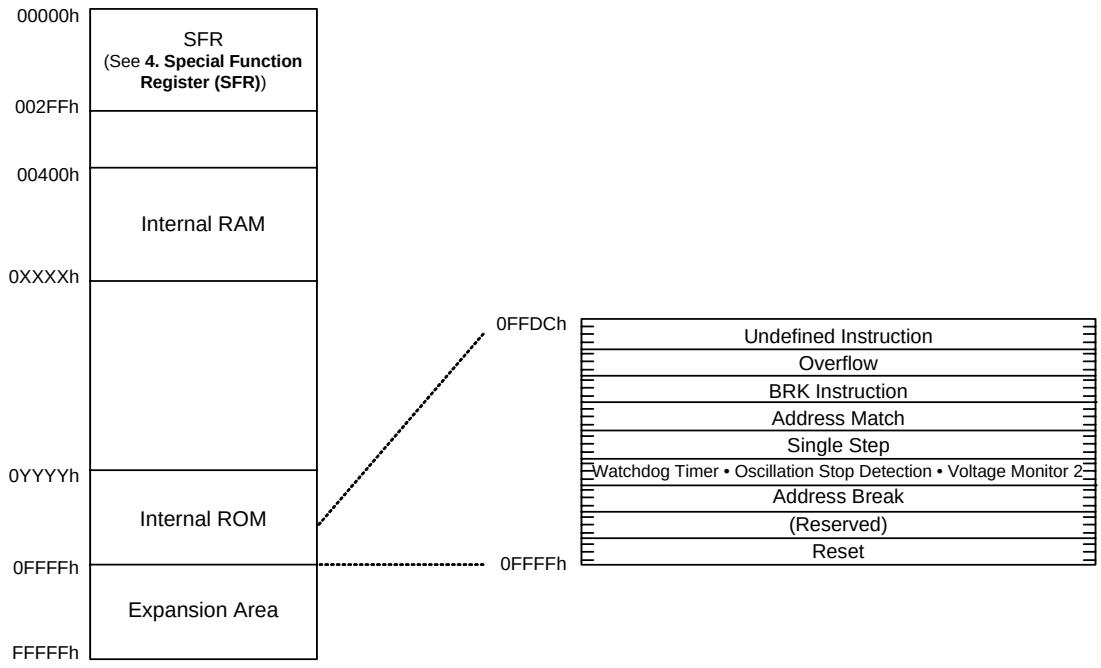
2.8.6 Overflow Flag (O)

The O flag is set to “1” when the operation resulted in an overflow; otherwise, “0”.

3. Memory

3.1 R8C/16 Group

Figure 3.1 is a Memory Map of the R8C/16 group. The R8C/16 group provides 1-Mbyte address space from addresses 00000h to FFFFFh.
The internal ROM is allocated lower addresses beginning with address 0FFFFh. For example, a 16-Kbyte internal ROM is allocated addresses 0C000h to 0FFFFh.
The fixed interrupt vector table is allocated addresses 0FFDCh to 0FFFFh. They store the starting address of each interrupt routine.
The internal RAM is allocated higher addresses beginning with address 00400h. For example, a 1-Kbyte internal RAM is allocated addresses 00400h to 007FFh. The internal RAM is used not only for storing data but for calling subroutines and stacks when interrupt request is acknowledged.
Special function registers (SFR) are allocated addresses 00000h to 002FFh. The peripheral function control registers are allocated them. All addresses, which have nothing allocated within the SFR, are reserved area and cannot be accessed by users.



NOTES:
1. Blank spaces are reserved. No access is allowed.

Part Number	Internal ROM		Internal RAM	
	Size	0YYYYh	Size	0XXXXh
R5F21164SP, R5F21164DSP	16 Kbytes	0C000h	1 Kbyte	007FFh
R5F21163SP, R5F21163DSP	12 Kbytes	0D000h	768 bytes	006FFh
R5F21162SP, R5F21162DSP	8 Kbytes	0E000h	512 bytes	005FFh

Figure 3.1 Memory Map of R8C/16 Group

4. Special Function Register (SFR)

SFR (Special Function Register) is the control register of peripheral functions. Tables 4.1 to 4.4 list the SFR information.

Table 4.1 SFR Information(1)[1]

Address	Register	Symbol	After Reset
0000h			
0001h			
0002h			
0003h			
0004h	Processor Mode Register 0	PM0	00h
0005h	Processor Mode Register 1	PM1	00h
0006h	System Clock Control Register 0	CM0	01101000b
0007h	System Clock Control Register 1	CM1	00100000b
0008h			
0009h	Address Match Interrupt Enable Register	AIER	00h
000Ah	Protect Register	PRCR	00h
000Bh			
000Ch	Oscillation Stop Detection register	OCD	00000100b
000Dh	Watchdog Timer Reset Register	WDTR	XXh
000Eh	Watchdog Timer Start Register	WDTS	XXh
000Fh	Watchdog Timer Control Register	WDC	00011111b
0010h	Address Match Interrupt Register 0	RMAD0	00h
0011h			00h
0012h			X0h
0013h			
0014h	Address Match Interrupt Register 1	RMAD1	00h
0015h			00h
0016h			X0h
0017h			
0018h			
0019h			
001Ah			
001Bh			
001Ch	Count Source Protection Mode Register	CSPR	00h
001Dh			
001Eh	$\overline{\text{INT0}}$ Input Filter Select Register	INT0F	00h
001Fh			
0020h	High-Speed On-Chip Oscillator Control Register 0	HRA0	00h
0021h	High-Speed On-Chip Oscillator Control Register 1	HRA1	When shipping
0022h	High-Speed On-Chip Oscillator Control Register 2	HRA2	00h
0023h			
002Ah			
002Bh			
002Ch			
002Dh			
002Eh			
002Fh			
0030h			
0031h	Voltage Detection Register 1[2]	VCA1	00001000b
0032h	Voltage Detection Register 2[2]	VCA2	00h[3] 01000000b[4]
0033h			
0034h			
0035h			
0036h	Voltage Monitor 1 Circuit Control Register [2]	VW1C	0000X000b[3] 0100X001b[4]
0037h	Voltage Monitor 2 Circuit Control Register [5]	VW2C	00h
0038h			
0039h			
003Ah			
003Bh			
003Ch			
003Dh			
003Eh			
003Fh			

X: Undefined

NOTES:

1. Blank spaces are reserved. No access is allowed.
2. Software reset, the watchdog timer reset or the voltage monitor 2 reset does not affect this register.
3. Owing to Hardware reset.
4. Owing to Power-on reset or the voltage monitor 1 reset.
5. Software reset, the watchdog timer reset or the voltage monitor 2 reset does not affect the b2 and b3.

Table 4.2 SFR Information(2)(1)

Address	Register	Symbol	After reset
0040h			
0041h			
0042h			
0043h			
0044h			
0045h			
0046h			
0047h			
0048h			
0049h			
004Ah			
004Bh			
004Ch			
004Dh	Key Input Interrupt Control Register	KUPIC	XXXXX000b
004Eh	A/D Conversion Interrupt Control Register	ADIC	XXXXX000b
004Fh	IIC Interrupt Control Register	IIC2AIC	XXXXX000b
0050h	Compare 1 Interrupt Control Register	CMP1IC	XXXXX000b
0051h	UART0 Transmit Interrupt Control Register	S0TIC	XXXXX000b
0052h	UART0 Receive Interrupt Control Register	S0RIC	XXXXX000b
0053h			
0054h			
0055h			
0056h	Timer X Interrupt Control Register	TXIC	XXXXX000b
0057h			
0058h	Timer Z Interrupt Control Register	TZIC	XXXXX000b
0059h	$\overline{\text{INT1}}$ Interrupt Control Register	INT1IC	XXXXX000b
005Ah	$\overline{\text{INT3}}$ Interrupt Control Register	INT3IC	XXXXX000b
005Bh	Timer C Interrupt Control Register	TCIC	XXXXX000b
005Ch	Compare 0 Interrupt Control Register	CMP0IC	XXXXX000b
005Dh	$\overline{\text{INT0}}$ Interrupt Control Register	INT0IC	XX00X000b
005Eh			
005Fh			
0060h			
0061h			
0062h			
0063h			
0064h			
0065h			
0066h			
0067h			
0068h			
0069h			
006Ah			
006Bh			
006Ch			
006Dh			
006Eh			
006Fh			
0070h			
0071h			
0072h			
0073h			
0074h			
0075h			
0076h			
0077h			
0078h			
0079h			
007Ah			
007Bh			
007Ch			
007Dh			
007Eh			
007Fh			

X: Undefined

NOTES:

1. Blank spaces are reserved. No access is allowed.

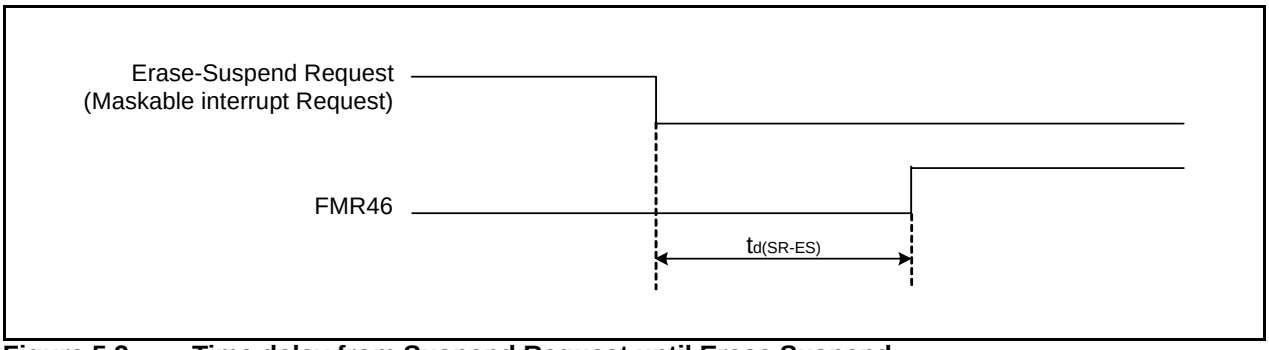


Figure 5.2 Time delay from Suspend Request until Erase Suspend

Table 5.6 Voltage Detection 1 Circuit Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
V_{det1}	Voltage Detection Level(3)		2.70	2.85	3.00	V
–	Voltage Detection Circuit Self Power Consumption	VCA26 = 1, V_{CC} = 5.0V	–	600	–	nA
$t_{d(E-A)}$	Waiting Time until Voltage Detection Circuit Operation Starts(2)		–	–	100	µs
Vccmin	Microcomputer Operating Voltage Minimum Value		2.7	–	–	V

NOTES:
1. The measurement condition is V_{CC} = AV_{CC} = 2.7V to 5.5V and T_{opr} = -40°C to 85 °C.
2. Necessary time until the voltage detection circuit operates when setting to “1” again after setting the VCA26 bit in the VCA2 register to “0”.
3. Hold V_{det2} > V_{det1}.

Table 5.7 Voltage Detection 2 Circuit Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
V_{det2}	Voltage Detection Level(4)		3.00	3.30	3.60	V
–	Voltage Monitor 2 Interrupt Request Generation Time(2)		–	40	–	µs
–	Voltage Detection Circuit Self Power Consumption	VCA27 = 1, V_{CC} = 5.0V	–	600	–	nA
$t_{d(E-A)}$	Waiting Time until Voltage Detection Circuit Operation Starts(3)		–	–	100	µs

NOTES:
1. The measurement condition is VCC = AVCC = 2.7V to 5.5V and Topr = -40°C to 85 °C.
2. Time until the voltage monitor 2 interrupt request is generated since the voltage passes V_{det1}.
3. Necessary time until the voltage detection circuit operates when setting to “1” again after setting the VCA27 bit in the VCA2 register to “0”.
4. Hold V_{det2} > V_{det1}.

Table 5.8 Reset Circuit Electrical Characteristics (When Using Voltage Monitor 1 Reset)

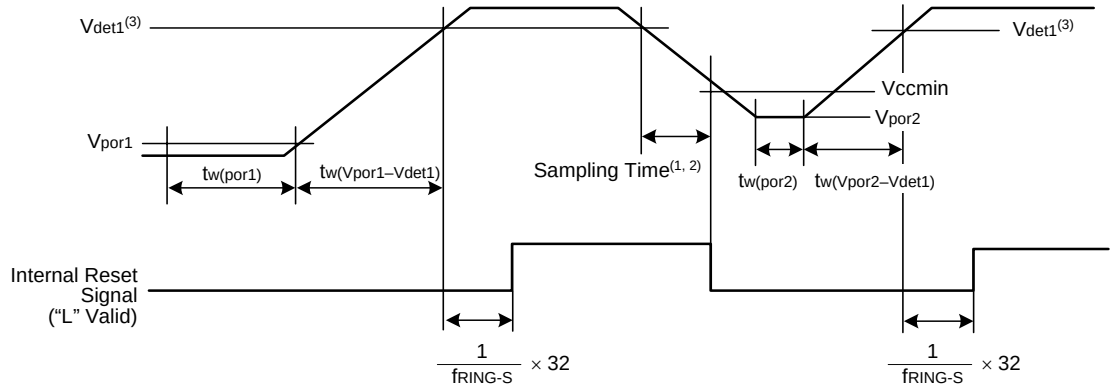
Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
V_{por2}	Power-On Reset Valid Voltage	-20°C ≤ Topr < 85°C	–	–	V_{det1}	V
$t_{w(Vpor2-Vdet1)}$	Supply Voltage Rising Time When Power-On Reset is Deasserted(1)	-20°C ≤ Topr < 85°C, $t_{w(por2)}$ ≥ 0s(3)	–	–	100	ms

NOTES:
1. This condition is not applicable when using with Vcc ≥ 1.0V.
2. When turning power on after the time to hold the external power below effective voltage (V_{por1}) exceeds10s, refer to **Table 5.9 Reset Circuit Electrical Characteristics (When Not Using Voltage Monitor 1 Reset)**.
3. $t_{w(por2)}$ is time to hold the external power below effective voltage (V_{por2}).

Table 5.9 Reset Circuit Electrical Characteristics (When Not Using Voltage Monitor 1 Reset)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
V_{por1}	Power-On Reset Valid Voltage	-20°C ≤ Topr < 85°C	–	–	0.1	V
$t_{w(Vpor1-Vdet1)}$	Supply Voltage Rising Time When Power-On Reset is Deasserted	0°C ≤ Topr ≤ 85°C, $t_{w(por1)}$ ≥ 10s(2)	–	–	100	ms
$t_{w(Vpor1-Vdet1)}$	Supply Voltage Rising Time When Power-On Reset is Deasserted	-20°C ≤ Topr < 0°C, $t_{w(por1)}$ ≥ 30s(2)	–	–	100	ms
$t_{w(Vpor1-Vdet1)}$	Supply Voltage Rising Time When Power-On Reset is Deasserted	-20°C ≤ Topr < 0°C, $t_{w(por1)}$ ≥ 10s(2)	–	–	1	ms
$t_{w(Vpor1-Vdet1)}$	Supply Voltage Rising Time When Power-On Reset is Deasserted	0°C ≤ Topr ≤ 85°C, $t_{w(por1)}$ ≥ 1s(2)	–	–	0.5	ms

NOTES:
1. When not using the voltage monitor 1 reset, use with Vcc≥ 2.7V.
2. $t_{w(por1)}$ is time to hold the external power below effective voltage (V_{por1}).



NOTES:
1. Hold the voltage of the microcomputer operation voltage range (Vccmin or above) within sampling time.
2. A sampling clock can be selected. Refer to **6. Voltage Detection Circuit** of Hardware Manual for details.
3. V_{det1} indicates the voltage detection level of the voltage detection 1 circuit. Refer to **6. Voltage Detection Circuit** of Hardware Manual for details.

Figure 5.3 Reset Circuit Electrical Characteristics

Table 5.10 High-speed On-Chip Oscillator Circuit Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
–	High-Speed On-Chip Oscillator Frequency When the Reset is Deasserted	V_{CC} = 5.0V, T_{opr} = 25 °C	–	8	–	MHz
–	High-Speed On-Chip Oscillator Frequency Temperature • Supplay Voltage Dependence	0 to +60 °C / 5 V ± 5 %(2)	7.44	–	8.56	MHz
		–20 to +85 °C / 2.7 to 5.5 V(2)	7.04	–	8.96	MHz
		–40 to +85 °C / 2.7 to 5.5 V(2)	6.80	–	9.20	MHz

NOTES:
1. The measurement condition is V_{CC} = AV_{CC} = 5.0V and T_{opr} = 25 °C.
2. The standard value shows when the HRA1 register is assumed as the value in shipping and the HRA2 register value is set to 00h.

Table 5.11 Power Supply Circuit Timing Characteristics

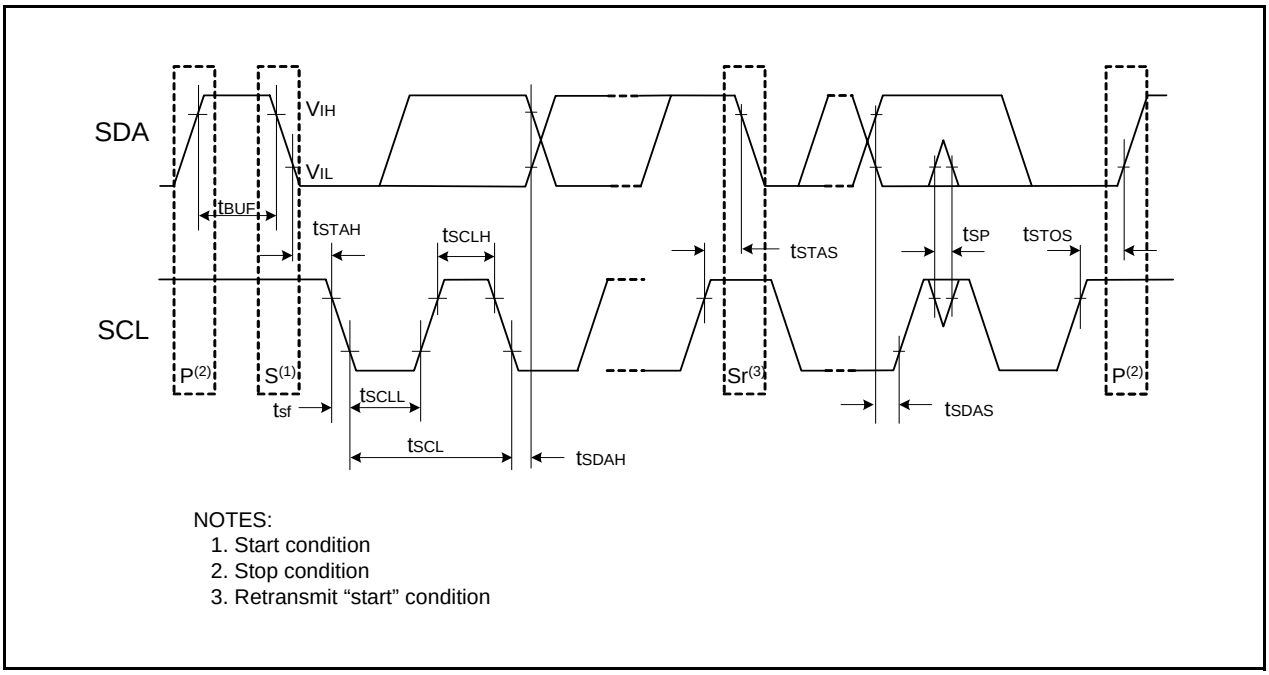
Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
$t_{d(P-R)}$	Time for Internal Power Supply Stabilization during Power-On(2)		1	–	2000	µs
$t_{d(R-S)}$	STOP Exit Time(3)		–	–	150	µs

NOTES:
1. The measurement condition is V_{CC} = AV_{CC} = 2.7 to 5.5V and T_{opr} = 25 °C.
2. Waiting time until the internal power supply generation circuit stabilizes during power-on.
3. Time until CPU clock supply starts since the interrupt is acknowledged to exit stop mode.

Table 5.12 Timing Requirements of I²C bus Interface (IIC) (1)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
t_{SCL}	SCL Input Cycle Time		$12t_{CYC}+600^{(2)}$	–	–	ns
t_{SCLH}	SCL Input “H” Width		$3t_{CYC}+300^{(2)}$	–	–	ns
t_{SCLL}	SCL Input “L” Width		$5t_{CYC}+300^{(2)}$	–	–	ns
t_{sf}	SCL, SDA Input Fall Time		–	–	300	ns
t_{SP}	SCL, SDA Input Spike Pulse Rejection Time		–	–	$1t_{CYC}^{(2)}$	ns
t_{BUF}	SDA Input Bus-Free Time		$5t_{CYC}^{(2)}$	–	–	ns
t_{STAH}	Start Condition Input Hold Time		$3t_{CYC}^{(2)}$	–	–	ns
t_{STAS}	Retransmit Start Condition Input SetUp Time		$3t_{CYC}^{(2)}$	–	–	ns
t_{STOS}	Stop Condition Input SetUp Time		$3t_{CYC}^{(2)}$	–	–	ns
t_{SDAS}	Data Input SetUp Time		$1t_{CYC}+20^{(2)}$	–	–	ns
t_{SDAH}	Data Input Hold Time		0	–	–	ns

NOTES:
1. V_{CC} = AV_{CC} = 2.7 to 5.5V, V_{SS} = 0V and Topr = -20 to 85 °C / -40 to 85 °C, unless otherwise specified.
2. $1t_{CYC}=1/f1(s)$



NOTES:
1. Start condition
2. Stop condition
3. Retransmit “start” condition

Figure 5.4 I/O Timing of I²C bus Interface (IIC)

Table 5.13 Electrical Characteristics (1) [Vcc = 5V]

Symbol	Parameter		Condition		Standard			Unit
					Min.	Typ.	Max.	
V_{OH}	Output “H” Voltage	Except X_{OUT}	I_{OH} = -5mA		V_{CC} – 2.0	–	V_{CC}	V
			I_{OH} = -200µA		V_{CC} – 0.3	–	V_{CC}	V
		X_{OUT}	Drive capacity HIGH	I_{OH} = -1mA	V_{CC} – 2.0	–	V_{CC}	V
			Drive capacity LOW	I_{OH} = -500µA	V_{CC} – 2.0	–	V_{CC}	V
V_{OL}	Output “L” Voltage	Except P1_0 to P1_3, X_{OUT}	I_{OL} = 5mA		–	–	2.0	V
			I_{OL} = 200µA		–	–	0.45	V
		P1_0 to P1_3	Drive capacity HIGH	I_{OL} = 15mA	–	–	2.0	V
			Drive capacity LOW	I_{OL} = 5mA	–	–	2.0	V
			Drive capacity LOW	I_{OL} = 200µA	–	–	0.45	V
		X_{OUT}	Drive capacity HIGH	I_{OL} = 1mA	–	–	2.0	V
			Drive capacity LOW	I_{OL} = 500µA	–	–	2.0	V
V_{T+}-V_{T-}	Hysteresis	$\overline{INT0}$, $\overline{INT1}$, $\overline{INT3}$, $\overline{KI0}$, $\overline{KI1}$, $\overline{KI2}$, $\overline{KI3}$, CNTR0, CNTR1, TCIN, RXD0			0.2	–	1.0	V
		$\overline{RESET}$			0.2	–	2.2	V
I_{IH}	Input “H” current		VI = 5V		–	–	5.0	µA
I_{IL}	Input “L” current		VI = 0V		–	–	-5.0	µA
R_{PULLUP}	Pull-Up Resistance		VI = 0V		30	50	167	kΩ
R_{fXIN}	Feedback Resistance	XIN			–	1.0	–	MΩ
f_{RING-S}	Low-Speed On-Chip Oscillator Frequency				40	125	250	kHz
V_{RAM}	RAM Hold Voltage		During stop mode		2.0	–	–	V

NOTES:
1. V_{CC} = AV_{CC} = 4.2 to 5.5V at T_{opr} = -20 to 85 °C / -40 to 85 °C, f(XIN)=20MHz, unless otherwise specified.

Timing Requirements (Unless otherwise specified: Vcc = 5V, Vss = 0V at Topr = 25 °C) [Vcc = 5V]

Table 5.15 XIN Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(XIN)}$	XIN Input Cycle Time	50	–	ns
$t_{WH(XIN)}$	XIN Input “H” Width	25	–	ns
$t_{WL(XIN)}$	XIN Input “L” Width	25	–	ns

Table 5.16 CNTR0 Input, CNTR1 Input, $\overline{INT1}$ Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CNTR0)}$	CNTR0 Input Cycle Time	100	–	ns
$t_{WH(CNTR0)}$	CNTR0 Input “H” Width	40	–	ns
$t_{WL(CNTR0)}$	CNTR0 input “L” Width	40	–	ns

Table 5.17 TCIN Input, $\overline{INT3}$ Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TCIN)}$	TCIN Input Cycle Time	400(1)	–	ns
$t_{WH(TCIN)}$	TCIN Input “H” Width	200(2)	–	ns
$t_{WL(TCIN)}$	TCIN input “L” Width	200(2)	–	ns

NOTES:
1. When using Timer C input capture mode, adjust the cycle time (1/ Timer C count source frequency x 3) or above.
2. When using Timer C input capture mode, adjust the width (1/ Timer C count source frequency x 1.5) or above.

Table 5.18 Serial Interface

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLKi Input Cycle Time	200	–	ns
$t_{W(CKH)}$	CLKi Input “H” Width	100	–	ns
$t_{W(CKL)}$	CLKi Input “L” Width	100	–	ns
$t_{d(C-Q)}$	TXDi Output Delay Time	–	50	ns
$t_{h(C-Q)}$	TXDi Hold Time	0	–	ns
$t_{su(D-C)}$	RXDi Input Setup Time	50	–	ns
$t_{h(C-D)}$	RCDi Input Hold Time	90	–	ns

Table 5.19 External Interrupt $\overline{INT0}$ Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{W(INH)}$	$\overline{INT0}$ Input “H” Width	250(1)	–	ns
$t_{W(INL)}$	$\overline{INT0}$ Input “L” Width	250(2)	–	ns

NOTES:
1. When selecting the digital filter by the $\overline{INT0}$ input filter select bit, use the $\overline{INT0}$ input HIGH width to the greater value, either (1/ digital filter clock frequency x 3) or the minimum value of standard.
2. When selecting the digital filter by the $\overline{INT0}$ input filter select bit, use the $\overline{INT0}$ input LOW width to the greater value, either (1/ digital filter clock frequency x 3) or the minimum value of standard.

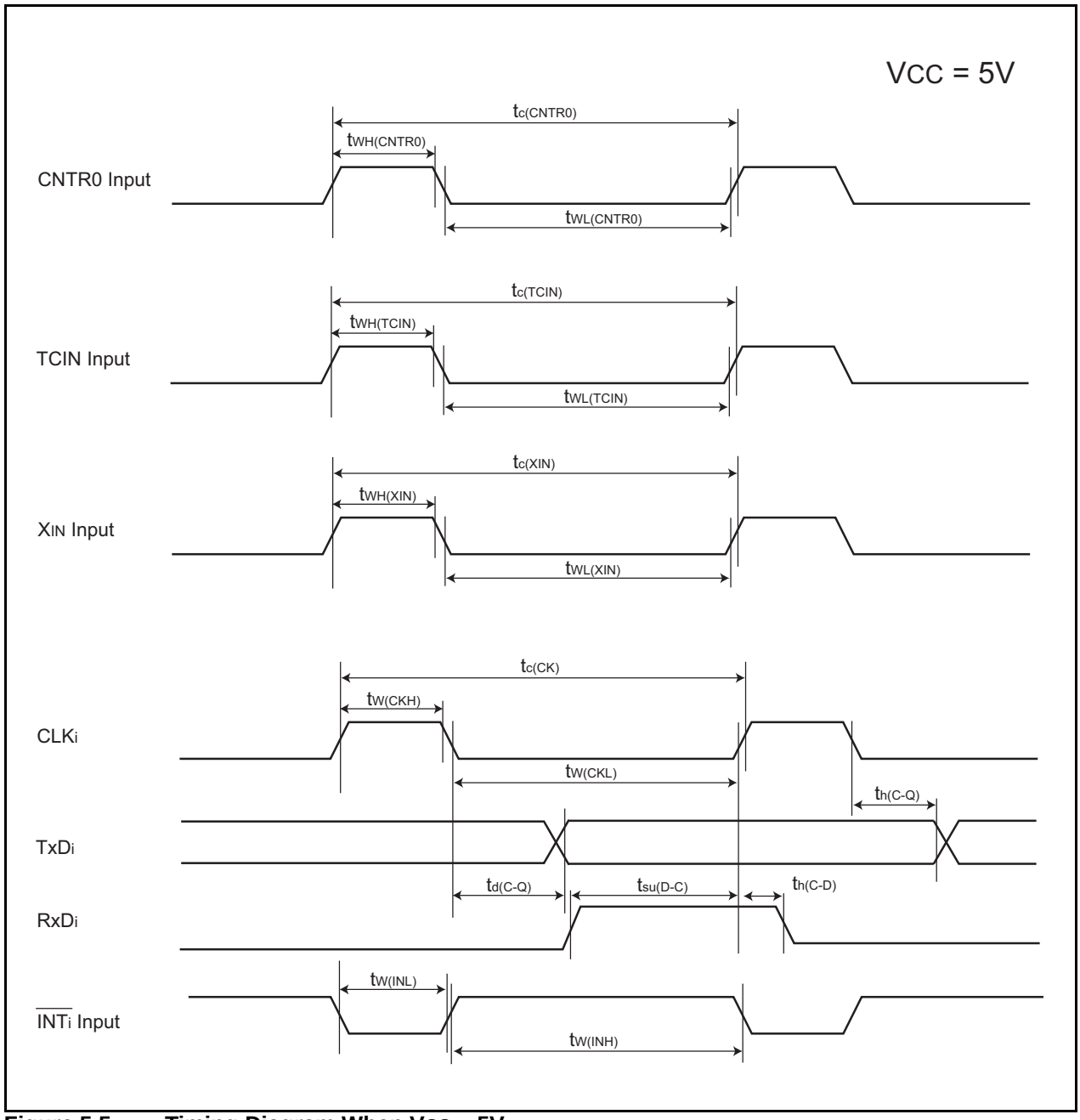


Figure 5.5 Timing Diagram When Vcc = 5V

Timing requirements (Unless otherwise specified: Vcc = 3V, Vss = 0V at Topr = 25 °C) [Vcc = 3V]

Table 5.22 XIN Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(XIN)}$	XIN Input Cycle Time	100	–	ns
$t_{WH(XIN)}$	XIN Input “H” Width	40	–	ns
$t_{WL(XIN)}$	XIN Input “L” Width	40	–	ns

Table 5.23 CNTR0 Input, CNTR1 Input, $\overline{INT1}$ Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CNTR0)}$	CNTR0 Input Cycle Time	300	–	ns
$t_{WH(CNTR0)}$	CNTR0 Input “H” Width	120	–	ns
$t_{WL(CNTR0)}$	CNTR0 Input “L” Width	120	–	ns

Table 5.24 TCIN Input, $\overline{INT3}$ Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TCIN)}$	TCIN Input Cycle Time	1,200(1)	–	ns
$t_{WH(TCIN)}$	TCIN Input “H” Width	600(2)	–	ns
$t_{WL(TCIN)}$	TCIN Input “L” Width	600(2)	–	ns

NOTES:
1. When using the Timer C input capture mode, adjust the cycle time (1/ Timer C count source frequency x 3) or above.
2. When using the Timer C input capture mode, adjust the width (1/ Timer C count source frequency x 1.5) or above.

Table 5.25 Serial Interface

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLKi Input Cycle Time	300	–	ns
$t_{W(CKH)}$	CLKi Input “H” Width	150	–	ns
$t_{W(CKL)}$	CLKi Input “L” Width	150	–	ns
$t_{d(C-Q)}$	TXDi Output Delay Time	–	80	ns
$t_{h(C-Q)}$	TXDi Hold Time	0	–	ns
$t_{su(D-C)}$	RXDi Input Setup Time	70	–	ns
$t_{h(C-D)}$	RCDi Input Hold Time	90	–	ns

Table 5.26 External Interrupt $\overline{INT0}$ Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{W(INH)}$	$\overline{INT0}$ Input “H” Width	380(1)	–	ns
$t_{W(INL)}$	$\overline{INT0}$ Input “L” Width	380(2)	–	ns

NOTES:
1. When selecting the digital filter by the $\overline{INT0}$ input filter select bit, use the $\overline{INT0}$ input HIGH width to the greater value, either (1/ digital filter clock frequency x 3) or the minimum value of standard.
2. When selecting the digital filter by the $\overline{INT0}$ input filter select bit, use the $\overline{INT0}$ input LOW width to the greater value, either (1/ digital filter clock frequency x 3) or the minimum value of standard.